Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

| HP 600B MT PC |

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>System fan</td>
<td>1</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cross screwdriver</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unfix system side cover screw*1 then remove side cover.
2. Remove front panel from system.
3. Displug all cable connector from motherboard and all devices.
4. Unfix Power LED & SW cable then remove it.
5. Unfix CR_front IO cable then remove it.
6. Unfix HDD device screw*4 then remove it from chassis.
7. Unfix ODD device screw*2 then remove it from chassis.
8. Unfix System Fan screw*3 then remove it from chassis.
9. Unfix MB screw*4 then remove it from chassis.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove side cover
   (1). Release screw on the access panel. (See photo 1)
   (2). Griping the tab at the end of access panel, pull toward the rear and remove from unit. (See photo 2)

![Photo 1](image)

![Photo 2](image)

2. Remove main bezel
   (1). Release 3 bezel latches from chassis by pulling outwards the bezel latches. (See photo 1)
(2). Rotate bezel away from chassis and lift unit to fully remove bezel. (See photo 2)

3. Unplug all cable
(1) HDD SATA and power cable  
(2) ODD SATA and power cable  
(3) CR_front I/O cable.  
(4) Power LED & SW cable
(5) System Fan cable
4. Remove power LED & SW cable
Unfix latch on the chassis and remove it.

5. Remove CR_front I/O
Unfix latch on the chassis, then press the latch and remove CR_front I/O cable from chassis.
Press the latch, then remove the cable.
6. Remove HDD device
Unfix HDD device screw*4 then remove it from chassis.

7. Remove ODD device
Unfix ODD device screw*2 then remove it from chassis.

8. Remove system fan device
Unfix system fan screw*3 then remove it from chassis.
9. Remove M/B device
Unfix M/B screw*4 then remove it from chassis.
Remove DDR device from MB
Press release latch on the DIMM slot, then remove it.
Remove coin battery from MB

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)